

**Amendments to the Claims:**

The **Listing of Claims** below represents the sole remaining claims in the Application.

**Listing of Claims:**

Claims 1-75 (previously cancelled).

76. (amended) A method of making a circuitized substrate, said method comprising:

providing a first dielectric layer having a first surface;

forming a first pattern of conductors and a second pattern of conductors spaced from said first pattern and electrically coupled thereto on said first surface of said first dielectric layer;

forming a common conductive line on said first surface of said first dielectric layer electrically connected to each of said conductors of said second pattern of conductors;

providing [[positioning]] a second dielectric layer in liquid form and flowing said second dielectric layer onto said first dielectric layer and substantially over said first and second patterns of conductors; and

thereafter terminating said electrical connections between each of said conductors of said second pattern of conductors and said common conductive line using a laser.

77. (cancelled)

78. (amended) The method of claim 76 [[77]] wherein said second dielectric layer comprises a soldermask.

79 - 81. (cancelled)

82. (previously presented) A method of making a circuitized substrate, said method comprising:

providing a first dielectric layer having a first surface;

forming a first pattern of conductors and a second pattern of conductors spaced from said first pattern and electrically coupled thereto on said first surface of said first dielectric layer;

forming a common conductive line on said first surface of said first dielectric layer electrically connected to each of said conductors of said second pattern of conductors;

thereafter terminating said electrical connections between each of said conductors of said second pattern of conductors and said common conductive line using a laser; and

positioning a semiconductor chip on said first dielectric layer and electrically coupling said semiconductor chip to said first pattern of conductors.

83. (previously presented) The method of claim 82 wherein said electrically coupling of said semiconductor chip to said first pattern of conductors is accomplished using a wirebonding operation.

84. (previously presented) The method of claim 82 wherein said semiconductor chip is electrically coupled to said first pattern of conductors using a plurality of solder balls.

Please add the following *new* claims:

85. (new) A method of making a circuitized substrate, said method comprising:
- providing a first dielectric layer having a first surface;
  - forming a first pattern of conductors and a second pattern of conductors spaced from said first pattern and electrically coupled thereto on said first surface of said first dielectric layer;
  - forming a common conductive line on said first surface of said first dielectric layer electrically connected to each of said conductors of said second pattern of conductors;
  - positioning a second dielectric layer substantially over said first and second patterns of conductors; and
  - thereafter terminating said electrical connections between each of said conductors of said second pattern of conductors and said common conductive line using a laser while simultaneously using said laser to provide openings in said second dielectric layer above respective ones of said electrical connections.
86. (new) The method of claim 85 wherein said laser also partially removes some of said first dielectric layer immediately below said electrical connections during said terminating of said connections.